DOCUMENT TITLE:
PACKAGE OUTLINE, 0.50MM GRID 3X3 BALL ARRAY USED ON DS2431, PKG CODE: BR622-1

DOC ID # 21-0377 NEW REV: A

ECN#: HQ-08-5741 EFFECTIVE DATE: 07/15/08

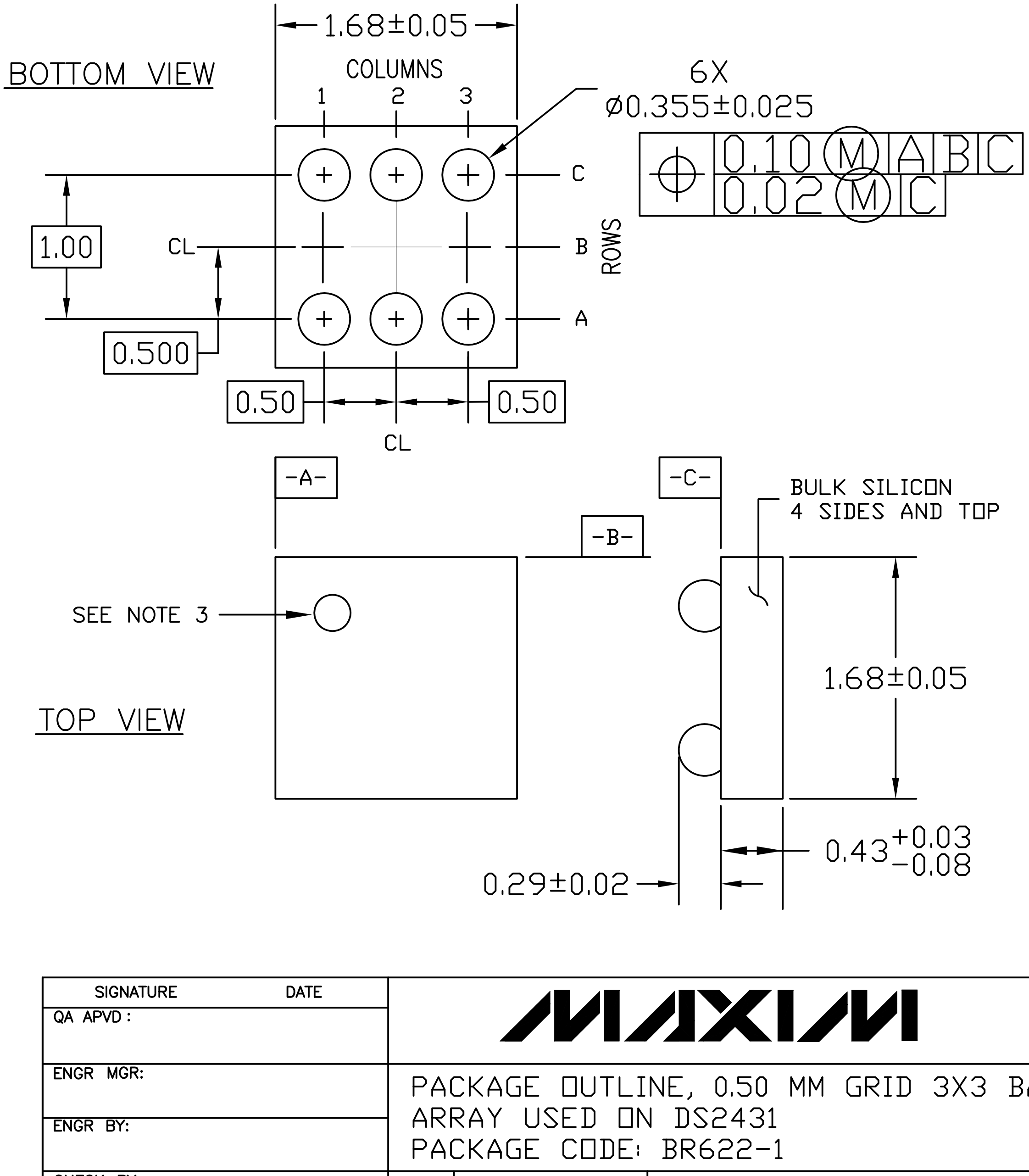
ORIGINATOR: JEFF WALKER

MOST RECENT CHANGES

FROM	TO
DALLAS DOCUMENT CONTROL SYSTEM DOC ID# 56-G7007-001 LOGO-DALLAS/MAXIM	INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL LOGO-MAXIM

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

NOTES:
1. DIMENSIONS: MM
2. BUMP MATERIAL: 63 Sn / 37 Pb (EUTECTIC)
3. LASER MARK INDICATING A1 CORNER ORIENTATION. NUMBER OF CHARACTERS AND LINES VARY BY PRODUCT.
4. ELECTRICAL NODES -- SEE PRODUCT DATA SHEET OR PROBE DOCUMENT
5. DEPOPULATED SOLDER BALLS: B1, B2, B3



SIGNATURE DATE				
QA APVD :				
ENGR MGR:	PACKAGE OUTLINE, 0.50 MM GRID 3X3 BALL ARRAY USED ON DS2431 PACKAGE CODE: BR622-1			
ENGR BY:				
CHECK BY:	SIZE A	FSCM NO.	DWG NO. 21-0377	REV A
DRAWN BY: B. MCCARTY 6/8/04	SCALE NONE		SHEET 1 of 1	

REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	ECN# HQ-08-5741. INITIAL RELEASE INTO MAXIM DOCUMENT CONTROL. LOGO-MAXIM	07/15/08	JW

	TITLE: PACKAGE OUTLINE, 0.50MM GRID 3X3 BALL ARRAY USED ON DS2431, PKG CODE: BR622-1		
	DOCUMENT I.D. 21-0377	**REVISION** A	**PAGE** 3